

Bill of Materials

TI DESIGNS

ISE4021 REV E2 Bill of Materials

TIDA-00372

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		ISE4021	Any	Printed Circuit Board	
2	BT1	1		2462	Keystone	2x AA Battery Holder, Through-hole mount	TH, 2x AA Battery Holder
3	C1, C2	2	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 5%, X7R, 0603	0603
4	C4	1	47uF	GRM32ER61C476KE15L	MuRata	CAP, CERM, 47 µF, 16 V, +/- 10%, X5R, 1210	1210
5	C5	1	2.2uF	C2012X5R1A225K/0.85	TDK	CAP, CERM, 2.2 µF, 10 V, +/- 10%, X5R, 0805	0805
6	C6	1	47uF	T495D476K020ATE100	Kemet	CAP, TA, 47 μF, 20 V, +/- 10%, 0.1 ohm, SMD	7343-31
7	C7	1	10uF	C2012X5R1E106K125AB	TDK	CAP, CERM, 10 μF, 25 V, +/- 10%, X5R, 0805	0805
8	C8	1	1uF	GRM216R61E105KA12D	MuRata	CAP, CERM, 1 μF, 25 V, +/- 10%, X5R, 0805	0805
9	D1	1	5V	SMAJ5.0CA	Littelfuse	Diode, TVS, Bi, 5 V, 400 W, SMA	SMA
10	D2	1	5V	1SS315TPH3F	Toshiba	Diode, Schottky, 5 V, 0.03 A, SOD-323	SOD-323
11	J1, J4, J6, J7	4		90120-0122	Molex	Header, 100mil, 2x1, Tin, TH	Header 2x1
12	J2, J5	2		SSW-110-23-F-D	Samtec	Connector, Receptacle, 100mil, 10x2, Gold plated, TH	10x2 Receptacle
13	J3	1	2x1	1715721	Phoenix Contact	Conn Term Block, 2POS, 5.08mm, TH	2POS Terminal Block
14	L1	1	6.8uH	SLF6028T-6R8M1R5-PF	TDK	Inductor, Shielded Drum Core, Ferrite, 6.8 µH, 1.5 A, 0.0354 ohm, SMD	Inductor, 6x2.8x6mm
15	Q1, Q2	2	-20V	CSD25310Q2	Texas Instruments	MOSFET, P-CH, -20 V, -20 A, SON 2x2mm	SON 2x2mm
16	R2	1	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200 k, 1%, 0.063 W, 0402	0402
17	R4, R5, R7	3	1.00Meg	CRCW06031M00FKEA	Vishay-Dale	RES, 1.00 M, 1%, 0.1 W, 0603	0603
18	R6, R10	2	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
19	R8	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
20	R9	1	392k	CRCW0603392KFKEA	Vishay-Dale	RES, 392 k, 1%, 0.1 W, 0603	0603
21	R11	1	178k	CRCW0603178KFKEA	Vishay-Dale	RES, 178 k, 1%, 0.1 W, 0603	0603
22	R12	1	40.2k	CRCW060340K2FKEA	Vishay-Dale	RES, 40.2 k, 1%, 0.1 W, 0603	0603
23	R13	1	2.67k	CRCW06032K67FKEA	Vishay-Dale	RES, 2.67 k, 1%, 0.1 W, 0603	0603
24	R14	1	48.7k	CRCW060348K7FKEA	Vishay-Dale	RES, 48.7 k, 1%, 0.1 W, 0603	0603
25	R15	1	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
26	SH-J1, SH-J4, SH- J6, SH-J7	4	1x2	2SN-BK-G	Samtec	Shunt, 2mm, Gold plated, Black	2mm Shunt, Closed
27	TP1	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
28	TP2, TP3, TP4	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
29	U1	1		TPS61029DRCR	Texas Instruments	Adjustable, 1.8-A Switch, 96% Efficient Boost Converter with Down-Mode, DRC0010A	
30	U2	1		TPL5110DDC	Texas Instruments	Ultra-Low Power System Timer with MOS driver and manual MSFET power ON, DDC0006A	DDC0006A
31	C3	0	1000pF	C1005C0G1E102J	TDK	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
32	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A
33	R3	0	1.00k	CRCW04021K00FKED	Vishay-Dale	RES, 1.00 k, 1%, 0.063 W, 0402	0402
34	R16	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402

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